



# 5<sup>th</sup> Generation CoolSiC<sup>™</sup> 1200V Schottky Diode

### SiC Diode

#### Features

- Revolutionary semiconductor material Silicon Carbide
- No reverse recovery current / no forward recovery
- Temperature independent switching behaviour
- Low forward voltage even at high operating temperature
- Tight forward voltage distribution
- Excellent thermal performance
- Extended surge current capability
- Specified dv/dt ruggedness
- Pb-free lead plating; RoHS compliant

### **Potential applications**

- Drives
- Industrial power supplies: Industrial UPS
- Solar central inverters and Solar string inverter

### **Product validation**

• Qualified for industrial applications according to the relevant tests of JEDEC 47/20/22

### Description

- System efficiency improvement over Si diodes
- Enabling higher frequency / increased power density solutions
- System size/cost savings due to reduced heatsink requirements and smaller magnetics
- Reduced EMI
- Highest efficiency across the entire load range
- Robust diode operation during surge events
- High reliability
- Related Links: <u>www.infineon.com/SiC</u>

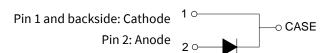




#### Key performance parameters

Туре	V <sub>DC</sub>	I <sub>F</sub>	Qc	T <sub>vj,max</sub>	Marking	Package
IDK10G120C5	1200 V	10 A	41nC	175°C	D1012C5	PG-TO263-2







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**Maximum ratings** 

### **1** Maximum ratings

Note:

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage $T_{\rm C} \ge 25^{\circ}{\rm C}$	V <sub>RRM</sub>	1200	V
Continuous forward current for $R_{th(j-c,max)}$ $T_c = 155^{\circ}C, D=1$ $T_c = 135^{\circ}C, D=1$ $T_c = 25^{\circ}C, D=1$	I <sub>F</sub>	10.0 15.2 31.9	A
Surge repetitive forward current, sine halfwave <sup>1</sup> $T_c=25$ °C, t <sub>p</sub> =10ms $T_c=100$ °C, t <sub>p</sub> =10ms	I <sub>F,RM</sub>	40 30	А
Surge non-repetitive forward current, sine halfwave $T_c$ =25°C, t <sub>p</sub> =10ms $T_c$ =150°C, t <sub>p</sub> =10ms	I <sub>F,SM</sub>	99 84	А
Non-repetitive peak forward current $T_c = 25^{\circ}C, t_p=10 \ \mu s$	I <sub>F,max</sub>	711	A
i <sup>2</sup> t value $T_{c} = 25^{\circ}C, t_{p}=10 \text{ ms}$ $T_{c} = 150^{\circ}C, t_{p}=10 \text{ ms}$	∫i²dt	49 35	A²s
Diode dv/dt ruggedness V <sub>R</sub> =0960 V	dv/dt	150	V/ns
Power dissipation for $R_{th(j-c,max)}$ $T_c = 25^{\circ}C$	P <sub>tot</sub>	165	W

Datasheet Pl www.infineon.com

<sup>&</sup>lt;sup>1</sup> Not subject to production test. The test was performed with 20000 pulses (two consecutive half-wave rectified sines with 10 ms period).

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#### Maximum ratings

Operating temperature	T <sub>vj</sub>	-55175	°C
Storage temperature	T <sub>stg</sub>	-55150	°C
Soldering temperature, reflow soldering (MSL1 according to JEDEC J-STD-020)	$T_{sold}$	260	°C



Thermal resistances

#### **Thermal resistances** 2

Devementer	Symbol	Conditions	Value			Unit
Parameter			min.	typ.	max.	Unit
Characteristic						
Diode thermal resistance, junction – case	R <sub>th(j-c)</sub>		-	0.7	0.91	K/W
Thermal resistance, junction – ambient	$R_{th(j-a)}$	Leaded	-	-	62	K/W



**Electrical Characteristics** 

#### **Electrical Characteristics** 3

#### Static Characteristics, at $T_{\nu j} \mbox{=} 25^\circ \mbox{C}$ , unless otherwise specified

Daramatar	Symbol	Conditions	Value			Unit
Parameter	Symbol		min.	typ.	max.	Unit
DC blocking voltage	V <sub>DC</sub>	T <sub>vj</sub> = 25°C, I <sub>R</sub> =50μA	1200	-	-	V
Diode forward voltage	17	<i>I</i> <sub>F</sub> = 10A, <i>T</i> <sub>νj</sub> =25°C	-	1.5	1.8	V
	VF	<i>I</i> <sub>F</sub> = 10A, <i>T</i> <sub>vj</sub> =150°C	-	2.0	-	
Reverse current	,	V <sub>R</sub> =1200V, <i>T</i> <sub>vj</sub> =25°C	-	4	62	μA
	/ <sub>R</sub>	V <sub>R</sub> =1200V, <i>T</i> <sub>vj</sub> =150°C	-	22	-	

#### Dynamic Characteristics, at $T_{\nu j} {=} 25^\circ C$ , unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
Parameter	Symbol		min.	typ.	max.	Unit
Total capacitive charge		V <sub>R</sub> =800V, T <sub>vj</sub> =150°C				
	Qc	$Q_C = \int_0^{V_R} C(V) dV$	-	41	-	nC
		<i>V</i> <sub>R</sub> =1 V, <i>f</i> =1 MHz	-	525	-	
Total Capacitance	С	<i>V</i> <sub>R</sub> =400 V, <i>f</i> =1 MHz	-	37	-	pF
		V <sub>R</sub> =800 V, <i>f</i> =1 MHz	-	29	-	

5<sup>th</sup> Generation CoolSiC<sup>™</sup> 1200V Schottky Diode SiC Diode Electrical Characteristics Diagrams



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### **Electrical Characteristics Diagrams**

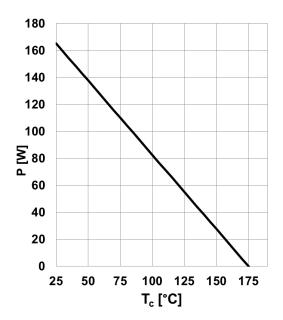


Figure 1. Power dissipation as function of case temperature,  $P_{tot}=f(T_c)$ ,  $R_{th(j-c),max}$ 

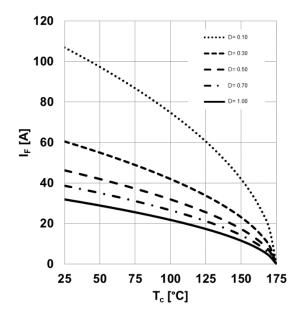


Figure 2. Diode forward current as function of temperature, parameter: T<sub>vj</sub>≤175°C, R<sub>th(j-c),max</sub>, D=duty cycle, V<sub>th</sub>, R<sub>diff</sub> @ T<sub>vj</sub>=175°C

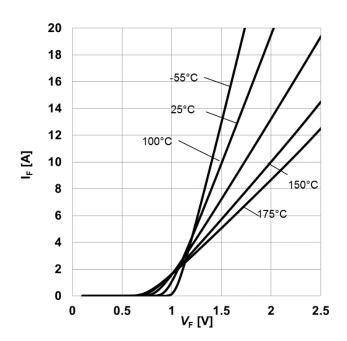


Figure 3. Typical forward characteristics,  $I_F=f(V_F)$ ,  $t_p=10 \mu s$ , parameter:  $T_{vj}$ 

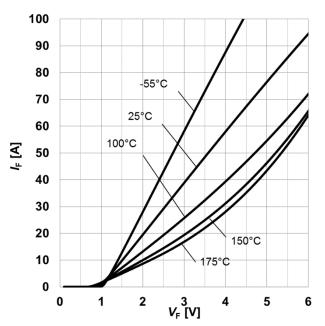


Figure 4. Typical forward characteristics in surge current,  $I_F = f(V_F)$ ,  $t_p = 10 \mu s$ , parameter:  $T_{vj}$ 

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#### **Electrical Characteristics Diagrams**

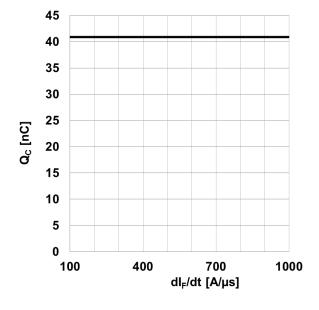
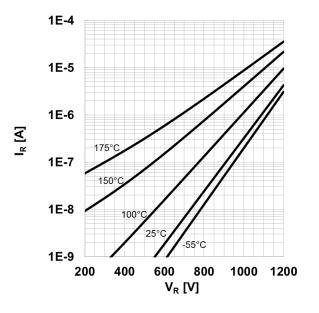
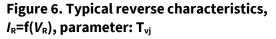
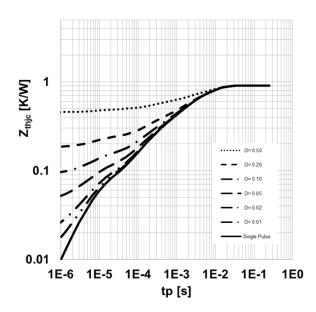
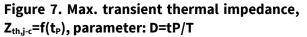


Figure 5. Typical capacitive charge as function of current slope,  $Q_c=f(dIF/dt)$ ,  $T_{vj}=150^{\circ}C$ 









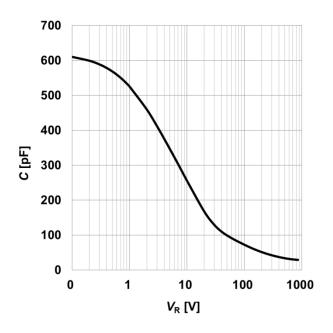


Figure 8. Typical capacitance as function of reverse voltage, C=f(V<sub>R</sub>);  $T_{vj}$ =25°C; f=1 MHz

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#### **Electrical Characteristics Diagrams**

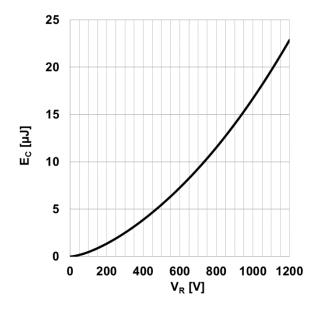
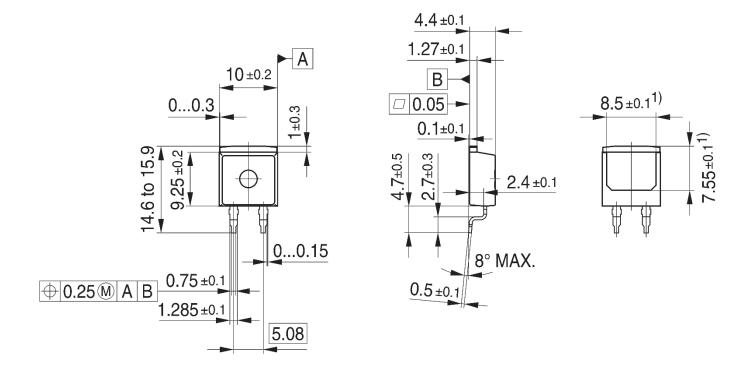


Figure 9. Typical capacitively stored energy as function of reverse voltage,  $E_c=f(V_R)$ 



## 5 Package Drawing

PG-TO263-2



#### 1) Typical

Metal surface min. X = 7.25, y = 6.9All metal surfaces: tin plated, except area of cut

All dimensions do not include mold flash or protrusions All dimensions are in units mm The drawings is in complicance with ISO 128-30, Projection Method 1 [→]



### **Revision history**

Document version	Date of release	Description of changes
V 2.0	2019-10-28	Final Datasheet
V 2.1	2021-07-14	Increased dv/dt ruggedness

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**Document reference** 

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